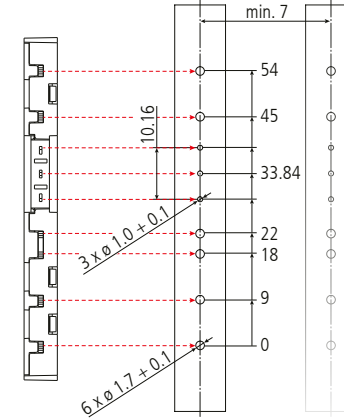
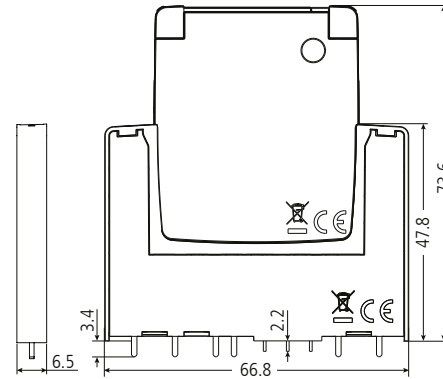
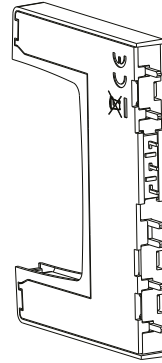
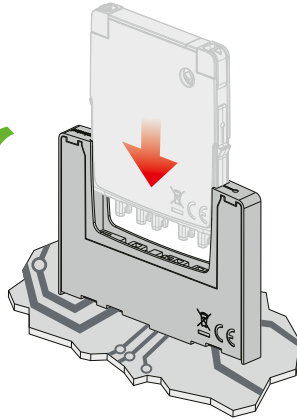
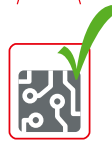
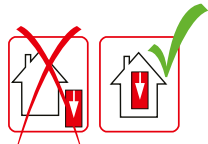


BLITZDUCTORconnect BCO BAS PCB

- DE Einbauanleitung
- GB Installation instructions
- IT Istruzioni di montaggio
- FR Instructions de montage
- NL Montagehandleiding
- ES Instrucciones de montaje
- PT Instruções de montagem
- DK Monteringsvejledning
- SE Monteringsanvisning
- FI Asennusohje
- GR Οδηγίες συναρμολόγησης
- PL Instrukcja montażu
- CZ Montážní návod
- TR Kurulum Talimatları
- RU Инструкция по монтажу
- CN 安装说明
- HU Szerelési útmutató
- JP 設置説明書

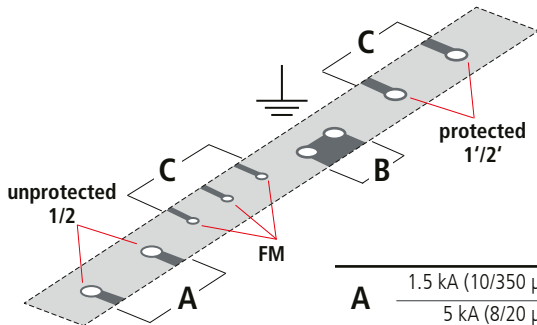
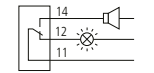


BCO BAS PCB

U _C *	180 V
I _{max} (8/20 μm)	20 kA
I _{imp} (10/350 μm)	3 kA
θ _{amb}	-40°C ... +80°C

*for plug-in protection module

AC:	125 V / 0.1 A
DC:	42 V / 0.5 A
	24 V / 1 A
	12 V / 2 A



	□ mm ²	35 μm	70 μm	105 μm	
A	1.5 kA (10/350 μs) 5 kA (8/20 μs)	0.10	3.0 mm 2.5 mm	1.5 mm 1.25 mm	1.0 mm 0.8 mm
B	3 kA (10/350 μs) 10 kA (8/20 μs)	0.25 0.20	6.0 mm 5.0 mm	3.0 mm 2.5 mm	2.0 mm 1.6 mm
C	FM / RS Contact Signal / signal line	kundenspezifisch / customer specific			

DE Hinweis zum Platinenlayout:



- Luft- und Kriechstrecken der Leiterbahn-Führung entsprechend der jeweiligen Norm der Applikation (z.B. Produktnorm, IPC-2221 [Richtlinie für das Design von Leiterplatten],...).
- ggf. Notwendigkeit für zusätzlichen Abstand zu
 - ➔ weiteren baugleichen BCO BAS PCB...
 - ➔ anderen Bauteilen auf der Leiterplatte...
 - ➔ Leiterbahnen
- EMV-gerechtes Design (z.B. Vermeiden von Schleifenbildung)
- die Lötpins der Erdungskontakte (B) zu einem verbinden
- unprotected/protected Leiterbahnen getrennt führen (A/C)

Hinweis zum Lötprozess:

- Löttemperatur max. 260 °C / 5 sec.
- Bei den Lötarbeiten darf **kein** Schutzmodul im jeweiligen Basisteil gesteckt sein!
- Die mech. Befestigung ist durch die Lötkontakte gegeben.
- ggf. das Basisteil mit Niederhalter fixieren

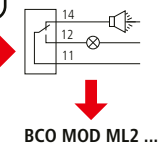
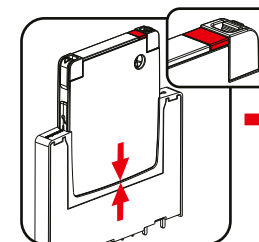
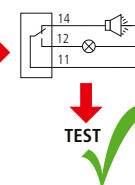
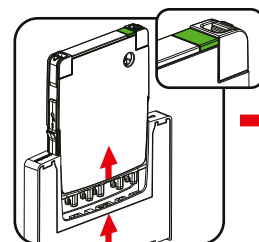
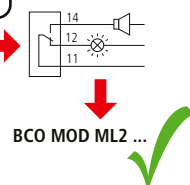
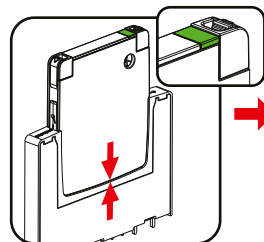
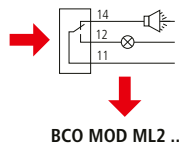
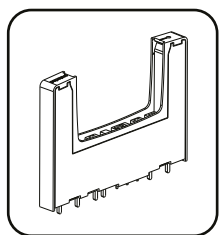


GB Notes on the printed circuit board layout:

- Air clearances and creepage distances of the track routing according to the standard relevant for the application (for example product standard, IPC-222 [Generic Standard on printed board designs], ...).
- Where required, an additional distance must be maintained from
 - ➔ other BCO BAS PCB... that are identical in construction
 - ➔ other components on the PCB...
 - ➔ PCB tracks
- EMC-compatible design (for example prevention of loops)
- Connect solder pins of earthing contacts (B)
- Route unprotected/protected tracks separately (A/C)

Notes on soldering process:

- Soldering temperature max. 260 °C / 5 sec.
- Before soldering the protection modules **must** be removed from the base part!
- Mechanical fixing is ensured by the solder contacts.
- If necessary fix basepart with hold-down clamp



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